

# **OLED SPECIFICATION**

Model No: OLED-128Y064C-LPP3N00000

## SPECIFICATION

Ver: C

## Module # : OLED-128Y064C-LPP3N00000

## **Global SAP #**: 0128Y064CLPP3N0000

APPROVED BY:		
(FOR CUSTOMER USE ONLY)		
	PCB VERSION:	DATA:

SALES BY	APPROVED BY	CHECKED BY	PREPARED BY
ISSUED DATE:			

MODLE NO :						
RECO	ORDS OF REVISIO	N	DOC. FIRST ISSUE			
VERSION	DATE	REVISED PAGE NO.	SUMMARY			
0	2011.10.26		First issue			
A	2012.01.17	14	Add Power Consumption			
В	2012.02.20	14	Add Optics			
			Characteristics			
C	2012.05.04	14	Add Brightness			

## **1. Module Classification Information**

OLED	-128	Y	064	С	L	Ρ	Ρ	3	Ν	00000
1	2	3	4	5	6	7	8	9	10	11

1	Brand : Vishay Intertechnology, Inc.						
2	Horizontal For	mat: 128 columns					
3	Display Type :	N→Character Type, H→Graphi	с Туре ,Ү→ТАВ Туре				
4	Vertical Forma	at: 64 lines					
5	Serials code:	С					
		A : Amber R : RED					
		B : Blue	C : Full color				
6	Emitting Color	G : Green	W : White				
		Y : Yellow Green	L : Yellow				
7	Polarizer	P : With Polarizer; N: Without F	Polarizer				
8	Display Mode	P : Passive Matrix ; A: Action Matrix					
9	Driver Voltage	3: 3.0 V; 5: 5.0V					
10	Touch Panel	N: Without touch panel; T: With touch panel					
11	Serial No.	00000: Sales code					

## **2. General Description**

ltem	Dimension	Unit			
Number of Characters	128 x 64 Dots	-			
Module dimension	89.7 × 47.2 × 3.4 (mm)	mm			
Active Area	61.41 × 30.69 (mm)	mm			
Pixel Pitch	0.48 × 0.48 (mm)	mm			
Pixel Size	0.45 × 0.45 (mm)	mm			
Weight	20.5	g			
Display Mode	Passive Matrix				
Display Color	Monochrome (Yellow)				
Drive Duty	1/64 Duty				

## **3. Absolute Maximum Ratings**

Parameter	Symbol	Min	Max	Unit	Notes
Supply Voltage for Logic	VDD	-0.3	3.5	V	1,2
Supply Voltage for Display	VCC	8	16	V	1,2
Operating Temperature	TOP	-40	80	°C	-
Storage Temperature	TSTG	-40	80	°C	-

Note 1: All the above voltages are on the basis of "VSS = 0V".

Note 2: When this module is used beyond the above absolute maximum ratings, permanent breakage of the module may occur. Also, for normal operations, it is desirable to use this module under the conditions according to Section 3. "Optics & Electrical Characteristics". If this module is used beyond these conditions, malfunctioning of the module can occur and the reliability of the module may deteriorate.

## 4. Block Diagram

### 4.1. POWER ON/OFF SEQUENCE & APPLICATION CIRCUIT

3.1.1 POWER ON/OFF SEQUENCE

Power ON sequence

- 1. Power ON VDD ,VDDIO
- **2.** After VDD ,VDDIO become stable , set RES# pin LOW (logic low) for at least 3us(t1) and then HIGH (logic high).
- 3. After set RES# pin LOW (logic low), wait for at least 3us(t2). Then Power ON Vcc. (1)
- **4.** After Vcc. become stable , send command AFh for display ON. DEG/COM will be ON after 100ms(tAF).



### **Power OFF sequence**

- 1. Send command AEh for display OFF.
- 2. Power OFF Vcc.(1),(2)
- 3. Wait for tOFF. Power OFF VDD ,VDDIO. (where Minimum tOFF=80ms,Typical tOFF=100ms)



Note:

- (1) Since an ESD protection circuit is connected between VDD ,VDDIO and Vcc, Vcc becomes lower than VDD and VDD , VDDIO is ON and Vcc is OFF as shown in the dotted line of Vcc in above figures.
- (2) Vcc should be disabled when it is OFF.



### **4.2 APPLICATION CIRCUIT**

### 4.3 INTERFACE 4.3.1 FUNCTION BLOCK DIAGRAM



### 4.4 PANEL LAYOUT DIAGRAM



### 4.5 GRAPHIC DISPLAY DATA RAM ADDRESS MAP

The GDDRAM is a bit mapped static RAM holding the bit pattern to be displayed. The size of the RAM is 132x64=8448bits

For mechanical flexibility, re-mapping on both Segment and Common outputs can be selected by software.



## **5.** Contour Drawing



## **6. Interface Pin Function**

No.	Symbol	Functi	on					
1	VCC	Power	Power supply for analog circuit.					
		Com ∖	Com Voltage Output. A capacitor should be					
2	VCOMH	connected						
			en this pin and `					
	IREF		ence current inp					
3			stor should be c	onnected betwo	een this p	oin		
		and VS						
4~11	D7~D0	Data b						
12	E/RD#		ead operation is					
13	R/W#		vrite operation is		it's pull l	OW.		
			Command cont					
14	D/C#		gh for write/read					
			w for write com	mand or read s	tatus.			
			signal input.					
15	RES#		it's low, initializa	ation of SSD13	05 is			
		execut						
16	CS#		elect input.					
			unicating Proto					
17	BS2		pins are MCU i	interface select	ion input.	. See		
		the						
		followi	ng table:	· · · · · · · · · · · · · · · · · · ·		1		
			68XX-paralle	80XX-paralle	Serial			
18	BS1			1	-			
		BS1 0 1 0						
		BS2 1 1 0						
19	VDD		supply for logic	circuit.				
20	NC	No connection.						
21	VSS		Ground.					
22	VSS	Groun	d.					

## 7. Optics & Electrical Characteristics

### 7.1INTERFACE TIMING CHART

8080-Series MCU Parallel Interface Timing Characteristics (VDD-VSS=2.4V to 3.5V, VDDIO=VDD,TA=25°C)

Symbol	Parameter	Min	Тур	Max	Unit
tcycle	Clock Cycle Time	300	-	-	ns
tAS	Address Setup Time	10	-	-	ns
tAH	Address Hold Time	0	-	-	ns
tDSW	Write Data Setup Time	40	-	-	ns
tDHW	Write Data Hold Time	7	-	-	ns
tDHR	Read Data Hold Time	20	-	-	ns
tOH	Output Disable Time	-	-	70	ns
tACC	Access Time	-	-	140	ns
tPWLR	Read Low Time	120	-	-	ns
tPWLW	Write Low Time	60	-	-	ns
tPWHR	Read High Time	60	-	-	ns
tPWHW	Write High Time	60	-	-	ns
tR	Rise Time	-	-	15	ns
tF	Fall Time	-	-	15	ns
tCS	Chip select setup time	0	-	-	ns
tCSH	Chip select setup hold time to read	0	-	-	ns
	signal				
tCSF	Chip select setup hold time	20	-	-	ns

#### 8080-seriesparallel interface characteristics (Form 1)

Write cycle(Form 1)









#### 7.2 DC Characteristics

Characteristics	Symbol	Condition	Min	Тур	Max	Unit
Supply Voltage for Logic	VDD	_	2.4	2.7	3.5	V
Supply Voltage for Display	VCC	—	14.5	15	15.5	V
High Level Input	VIH	lout = 100µA,3.3MHz	0.8×VDD		VDD	V
Low Level Input	VIL	lout = 100µA,3.3MHz	0		0.2×VDD	V
High Level Output	VOH	lout =100µA,3.3MHZ	0.9×VDD	_	VDD	V
Low Level Input	VOL	lout =100µA,3.3MHZ	0		0.1×VDD	V
Operating Current for VDD	IDD	Note 4		90	_	mA
(Panel attached)	טטו	Note 5		101	_	mA
Operating Current for VCC	ICC	Note 4		15	—	mA
(Panel attached)		Note 5	—	17	—	mA
Sleep Mode Current for VDD	IDD, SLEEP		_		10	μA
Sleep Mode Current for VCC	ICC, SLEEP		_	_	10	μA
Power Consumption		50% Display Area Turn on		297		mW
Power Consumption		100% Display Area Turn on		333	_	mW

Note 3: Brightness (Lbr) and Supply Voltage for Display (Vcc) are subject to the change of the panel characteristics and the customer's request.

Note 4:  $V_{DD} = 3.3V$ ,  $V_{CC} = 13.7V$ , 50% Display Area Turn on. (Contrast value =0x80) Note 5:  $V_{DD} = 3.3V$ ,  $V_{CC} = 13.2V$ , 100% Display Area Turn on.(Contrast value = 0x80) (Base on 80 nits on 50% checkboard and include DC to DC circuit.)

\* Software configuration follows Section 4.4 Initialization.

### 7.3 Optics Characteristics

Characteristics	Symbol	Condition	Min	Тур	Max	Unit
C.I.E. (Yellow)	(x)	Without Polarizer	0.44	0.48	0.52	
	(y)	without Polarizer	0.46	0.50	0.54	
Dark Room Contrast	CR		_	>2000:1		_
View Angle			>160	_	—	
Brightness	Yellow	With Polarizer	60	80		cd/m <sup>2</sup>

## 8. Reliability

### 8.1 Contents of Reliability Tests

Item	Condi	tions	Criteria
High Temperature Operation	80	°C,240hrs	
Low Temperature Operation	-40	°C,240hrs	<b>-</b>
High Temperature Storage	80	°C,240hrs	The operational
Low Temperature Storage	-40	°C,240hrs	functions work
High Temperature/Humidity	60	° <b>C,40% 80</b> 40,20	functions work.
Operation/ Thermal Shock	24cycle	es 1 hr dwell	

\* The samples used for the above tests do not include polarizer.

\* No moisture condensation is observed during tests.

### 8.2 Lifetime

Parameter	Min	Тур	Max	Unit	Condition	Notes
Operating Life Time		100,000	_	Hrs	80 cd/m2, 50% Checkerboard	6

Note 6: The average operating lifetime at room temperature is estimated by the accelerated operation at high temperature conditions.

### 8.3 Failure Check Standard

After the completion of the described reliability test, the samples were left at room temperature for 2 hrs prior to conducting the failure test at  $23\pm5^{\circ}C$ ;  $55\pm15^{\circ}RH$ .

# 9. Inspection specification

NO	Item	Criterion				AQL
01	Electrical Testing	defect. 1.2 Missing cha 1.3 Display ma 1.4 No function	aracter , d Ifunction. or no dis nsumption gle defect uct types.	ot or icon. play. exceeds produc	egment contrast	0.65
02	Black or white spots (display only)	<ul> <li>2.1 White and black spots on display ≤0.25mm, no more than three white or black spots present.</li> <li>2.2 Densely spaced: No more than two spots or lines within 3mm</li> </ul>			2.5	
03	Black spots, white spots, contaminatio n (non-display)	<ul> <li>3.1 Round type following drawing dr</li></ul>	ng / 2 ↓ ↓ ↓	SIZE $\Phi \le 0.10$ $0.10 <$ $\Phi \le 0.20$ $0.20 <$ $\Phi \le 0.25$ $0.25 < \Phi$ ving drawing)           Width           W $\le 0.02$ $0.02 < W \le 0.03$ $0.03 < W \le 0.05$ $0.05 < W$	dense 2 1 0 Acceptable Q TY Accept no dense 2	2.5
04	Polarizer bubbles	If bubbles are v judge using bla specifications, easy to find, m check in specif direction.	visible, ack spot not ust	Size Φ         Φ $\leq$ 0.20         0.20<Φ $\leq$ 0.50         0.50<Φ $\leq$ 1.00         1.00<Φ	Acceptable Q TY Accept no dense 3 2 0 3	2.5

NO Item	1	Criterion					
05 Scratc	nes Follow NO.3 Black sp	Follow NO.3 Black spots, white spots, contamination					
	nesFollow NO.3 Black spSymbols Define: x: Chip length k: Seal width L: Electrode pad length 6.1 General glass ch 6.1.1 Chip on panel st6.1 General glass ch 6.1.1 Chip on panel stImage: second state of the second state of t	oots, white spots, conta y: Chip width z: C t: Glass thickness a: gth:	hip thickness Side length /een panels: $x \in Chip length$ $x \le 1/8a$ $x \le 1/8a$	AQL 2.5			
	6.1.2 Corner crack:	y: Chip width Not over viewing area Not exceed 1/3k pre chips, x is the total	<b>y</b> x: Chip length $x \le 1/8a$ $x \le 1/8a$ length of each chip.				



NO	Item	Criterion	AQL
07	Cracked glass	With extensive crack is not acceptable.	2.5
08	Backlight elements	<ul> <li>8.1 Illumination source flickers when lit.</li> <li>8.2 Spots or scratched that appear when lit must be judged. Using Spot, lines and contamination standards.</li> <li>8.3 Backlight doesn't light or color wrong.</li> </ul>	0.65 2.5 0.65
09	Bezel	<ul><li>9.1 Bezel may not have rust, be deformed or have fingerprints, stains or other contamination.</li><li>9.2 Bezel must comply with job specifications.</li></ul>	2.5 0.65
10	PCB \ COB	<ul> <li>10.1 COB seal may not have pinholes larger than 0.2mm or contamination.</li> <li>10.2 COB seal surface may not have pinholes through to the IC.</li> <li>10.3 The height of the COB should not exceed the height indicated in the assembly diagram.</li> <li>10.4 There may not be more than 2mm of sealant outside the seal area on the PCB. And there should be no more than three places.</li> <li>10.5 No oxidation or contamination PCB terminals.</li> <li>10.6 Parts on PCB must be the same as on the production characteristic chart. There should be no wrong parts, missing parts or excess parts.</li> <li>10.7 The jumper on the PCB should conform to the product characteristic chart.</li> <li>10.8 If solder gets on bezel tab pads, LED pad, zebra pad or screw hold pad, make sure it is smoothed down.</li> </ul>	<ol> <li>2.5</li> <li>2.5</li> <li>2.5</li> <li>0.65</li> <li>0.65</li> <li>2.5</li> </ol>
11	Soldering	<ul> <li>11.1 No un-melted solder paste may be present on the PCB.</li> <li>11.2 No cold solder joints, missing solder connections, oxidation or icicle.</li> <li>11.3 No residue or solder balls on PCB.</li> <li>11.4 No short circuits in components on PCB.</li> </ul>	2.5 2.5 2.5 0.65

12General appearanceGeneral appearance12.6 The residual rosin or tin oil of soldering (component or chip component) is not burned into brown or black color.0.6 0.6	NO	Item	Criterion	AQL
12.9 Pin loose or missing pins.		General	<ul> <li>12.1 No oxidation, contamination, curves or, bends on interface Pin (OLB) of TCP.</li> <li>12.2 No cracks on interface pin (OLB) of TCP.</li> <li>12.3 No contamination, solder residue or solder balls on product.</li> <li>12.4 The IC on the TCP may not be damaged, circuits.</li> <li>12.5 The uppermost edge of the protective strip on the interface pin must be present or look as if it cause the interface pin to sever.</li> <li>12.6 The residual rosin or tin oil of soldering (component or chip component) is not burned into brown or black color.</li> <li>12.7 Sealant on top of the ITO circuit has not hardened.</li> <li>12.8 Pin type must match type in specification sheet.</li> <li>12.10 Product packaging must the same as specified on packaging specification and structure must conform to</li> </ul>	AQL 2.5 0.65 2.5 2.5 2.5 2.5 2.5 0.65 0.65 0.65 0.65

### Pattern Check (Display On) in Active Area

Check Item	Classification	Criteria
No Display	Major	
Missing Line	Major	
Pixel Short	Major	
Darker Pixel	Major	
Wrong Display	Major	
Un-uniform	Major	



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